

**AMENDMENTS TO THE SPECIFICATION:**

On page 1, after title of the invention, please insert the following header:

--FIELD OF THE INVENTION--

On page 1 after line 7, please insert the following header:

--BACKGROUND OF THE INVENTION --

On page 1 after line 31, please insert the following header:

--SUMMARY OF THE INVENTION --

On page 2 after line 25, please enter the following header:

--BRIEF DESCRIPTION OF THE DRAWINGS--

On page \_ after line \_, please insert the following header:

--DETAILED DESCRIPTION OF THE INVENTION--

**Please replace the 1<sup>st</sup> paragraph on page 7, lines 1-17, with the following amended paragraph:**

Figure 3B illustrates the case of initially thinning a ceramic capacitor with an attached electrode. In fact, ceramic capacitors may have end terminals 35 of a material incompatible with the metallization which will be applied during the step of redistributing the terminals (step 15 described below) and which is fixed by chip terminal metallization technology. It may thus be necessary to process the thinned capacitors with non-oxidizable metals or alloys (for example gold or gold-palladium). In the exemplary embodiment described in Figure 3B, electrodes 39 in the form of a strip or wire are bonded to the end terminals 35 by means of conductive adhesive 38 (for example containing silver) or by brazing. After thinning (cut C), the non-oxidizable electrodes 39 have sections 391 which can fulfill the function of terminals 221 of the passive component (Figure 2A).